



General Description

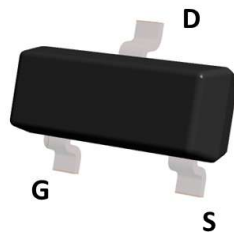
- Trench Power LV MOSFET technology
- High Power and current handing capability
- ESD Protected Up to 3.5KV (HBM)

Applications

- PWM application
- Load switch

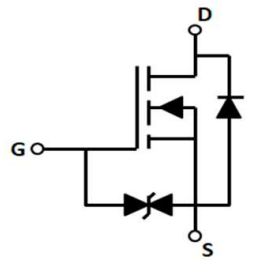
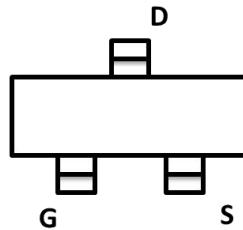
Product Summary

V_{DS}	20	V
$R_{DS(on), Typ @ V_{GS}=4.5V}$	16	mΩ
I_D	7.0	A



Top View

SOT-23



Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	20	V
Gate-source Voltage		V_{GS}	± 12	V
Drain Current	$T_A=25^{\circ}\text{C}$ @ Steady State	I_D	7.0	A
	$T_A=70^{\circ}\text{C}$ @ Steady State		5.6	
Pulsed Drain Current ^A		I_{DM}	30	A
Total Power Dissipation @ $T_A=25^{\circ}\text{C}$		P_D	1.3	W
Thermal Resistance Junction-to-Ambient @ Steady State		$R_{\theta JA}$	96	$^{\circ}\text{C}/\text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^{\circ}\text{C}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±10V, V _{DS} =0V		2.5	±10	μA
		V _{GS} = ±5V, V _{DS} =0V		300	±1000	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	0.45	0.62	1.0	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 4.5V, I _D =7.0A		16	18	mΩ
		V _{GS} = 2.5V, I _D =4.0A		19	22	
		V _{GS} = 1.8V, I _D =3.0A		25	39	
Diode Forward Voltage	V _{SD}	I _S =7.0A, V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				7.0	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHZ		640		pF
Output Capacitance	C _{oss}			147		
Reverse Transfer Capacitance	C _{rss}			78		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =4.5V, V _{DS} =10V, I _D =7.0A		8.1		nC
Gate Source Charge	Q _{gs}			2.4		
Gate Drain Charge	Q _{gd}			3		
Turn-on Delay Time	t _{D(on)}	V _{GS} =4.5V, V _{DD} =10V, R _L =1.5Ω, R _{GEN} =3Ω		1.2		ns
Turn-on Rise Time	t _r			2.4		
Turn-off Delay Time	t _{D(off)}			22		
Turn-off Fall Time	t _f			7		

A. Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Performance Characteristics

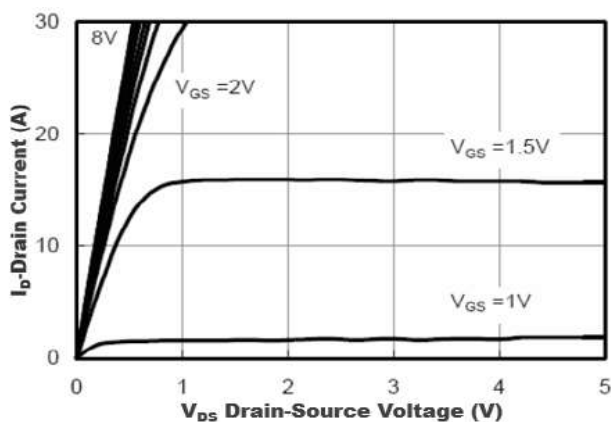


Figure1. Output Characteristics

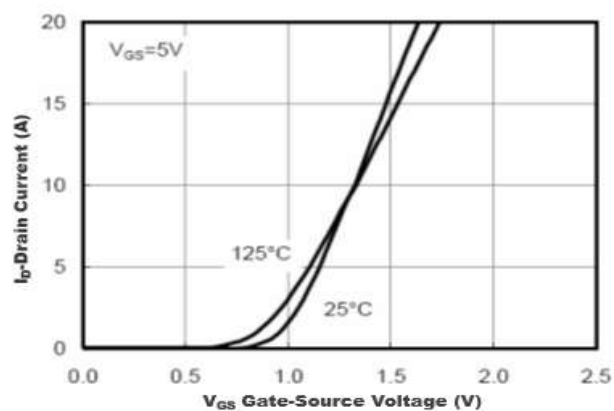


Figure2. Transfer Characteristics

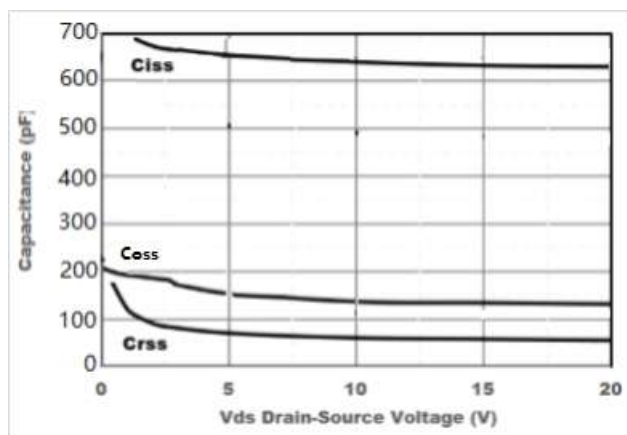


Figure3. Capacitance Characteristics

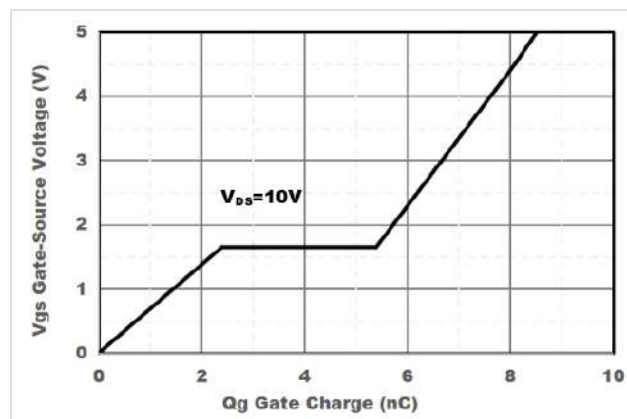


Figure4. Gate Charge

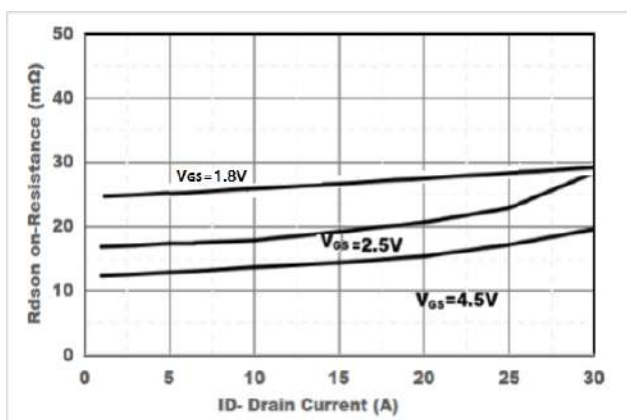


Figure5. Drain-Source on Resistance

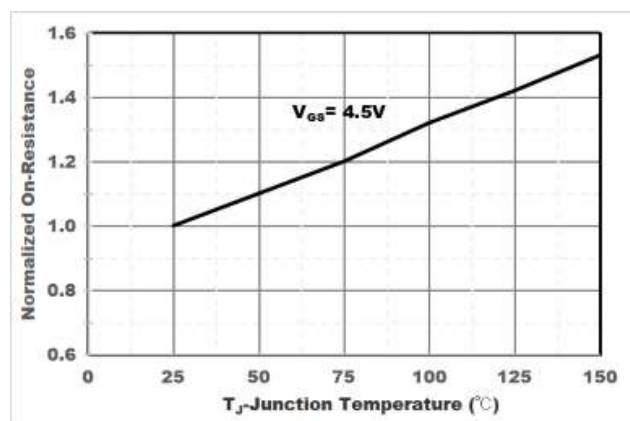


Figure6. Drain-Source on Resistance

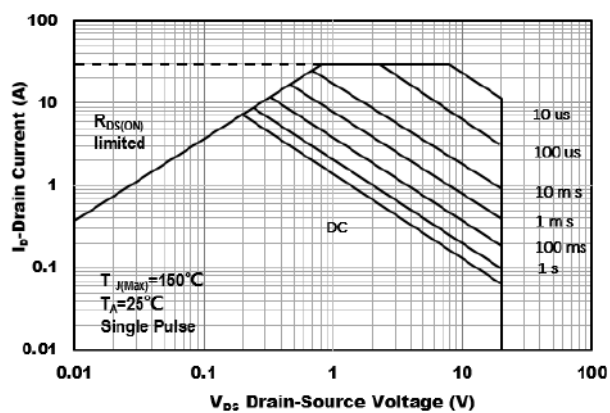


Figure7. Safe Operation Area

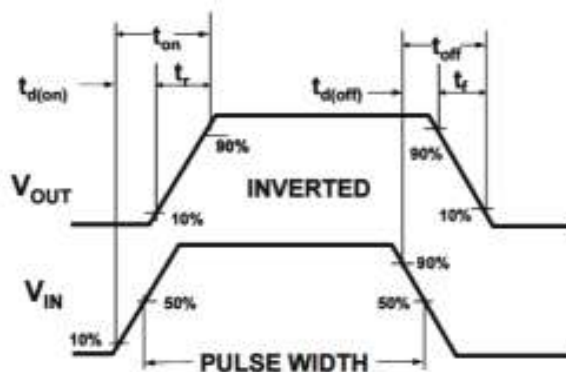
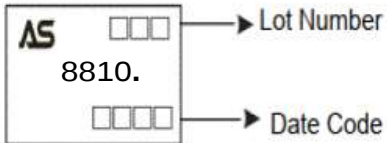


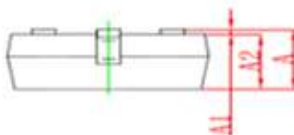
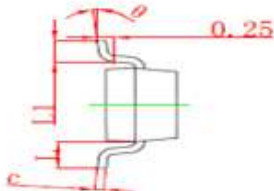
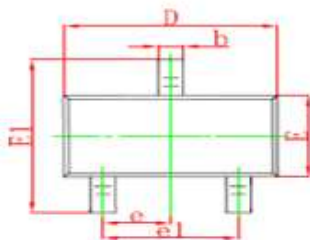
Figure8. Switching wave

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM3416EZA-R	8810.	SOT-23	Tape&Reel	3000/Reel

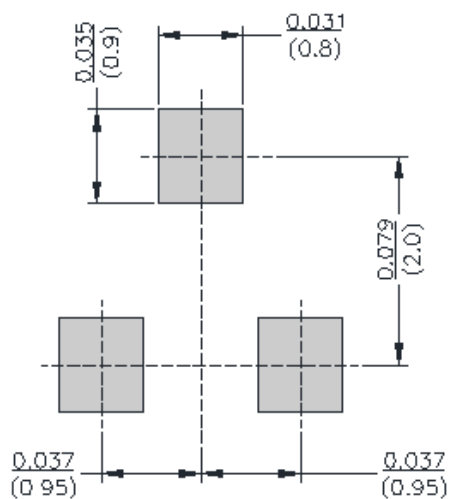
PACKAGE	MARKING
SOT-23	 The marking diagram shows a rectangular package with the following markings: 'AS' logo, '8810.', and two sets of four boxes. Arrows point from the top set of boxes to 'Lot Number' and from the bottom set of boxes to 'Date Code'.

SOT-23 Package information



Symbol	Dimentions in Millimeter		Dimentions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0 °	8 °	0 °	8 °

■SOT-23 Suggested Pad Layout



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